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ON Semiconductor®

FQP2P40

P-Channel QFET® MOSFET -400 V, -2.0 A, 6.5 Ω

Description

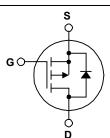
These P-Channel enhancement mode power field effect transistors are produced using ON Semiconductor's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for electronic lamp ballast based on complimentary half bridge.

Features

- -2.0 A, -400 V, $R_{DS(on)}$ = 6.5 Ω (Max.) @ V_{GS} = -10 V
- Low Gate Charge (Typ. 10 nC)
- Low Crss (Typ. 6.5 pF)
- · Fast Switching
- · 100% Avalanche Tested
- · Improved dv/dt Capability





Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted.

	- 0			
Symbol	Parameter		FQP2P40-F080	Unit
V _{DSS}	Drain-Source Voltage		-400	V
I _D	Drain Current - Continuous (T _C = 25°C	C)	-2.0	Α
	- Continuous (T _C = 100°	°C)	-1.27	Α
I_{DM}	Drain Current - Pulsed	(Note 1)	-8.0	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	120	mJ
I _{AR}	Avalanche Current	(Note 1)	-2.0	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	6.3	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-4.5	V/ns
P _D	Power Dissipation (T _C = 25°C)		63	W
	- Derate Above 25°C		0.51	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	ge	-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering 1/8" from Case for 5 Seconds	g,	300	°C

Thermal Characteristics

Symbol	Parameter	FQP2P40-F080	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.98	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP2P40-F080	FQP2P40	TO-220	Tube	N/A	N/A	50 units

Elerical Characteristics

T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-400			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		-		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -400 V, V _{GS} = 0 V			-1	μΑ
	Zero Gate voltage Drain Current	V _{DS} = -320 V, T _C = 125°C			-10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 30 V, V _{DS} = 0 V			100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-3.0		-5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = -10 \text{ V}, I_D = -1.0 \text{ A}$	1	5.0	6.5	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = -50 \text{ V}, I_{D} = -1.0 \text{ A}$	-	1.42	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = -25 V, V _{GS} = 0 V,	 270	350	pF
C _{oss}	Output Capacitance	f = 1.0 MHz	 45	60	pF
C _{rss}	Reverse Transfer Capacitance		 6.5	8.5	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = -200 V, I _D = -2.0 A,	 9	30	ns
t _r	Turn-On Rise Time	$V_{GS} = -10 \text{ V, R}_{G} = 25 \Omega$	 33	75	ns
t _{d(off)}	Turn-Off Delay Time		 22	55	ns
t _f	Turn-Off Fall Time	(Note 4)	 25	60	ns
Qg	Total Gate Charge	V _{DS} = -320 V, I _D = -2.0 A,	 10	13	nC
Q_{gs}	Gate-Source Charge	V _{GS} = -10 V	 2.1		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	 5.5		nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current				-2.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				-8.0	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -2.0 \text{ A}$			-5.0	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = -2.0 \text{ A},$		250		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$	-	0.85		μС

Notes

- 1. Repetitive rating : pulse-width limited by maximum junction temperature.
- 2. L = 52.5 mH, I $_{AS}$ = -2.0 A, V $_{DD}$ = -50 V, R $_{G}$ = 25 $\Omega,$ Starting $\,$ T $_{J}$ = 25 $^{\circ}C.$
- 3. I $_{SD} \leq$ -2.0 A, di/dt \leq 200 A/ μ s, V $_{DD} \leq$ BV $_{DSS,}$ Starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature.

Typical Performance Characteristics

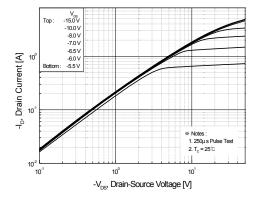


Figure 1. On-Region Characteristics

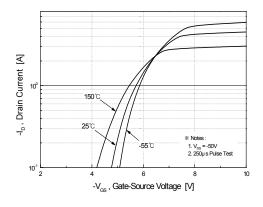


Figure 2. Transfer Characteristics

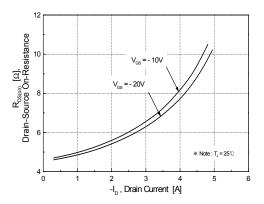


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

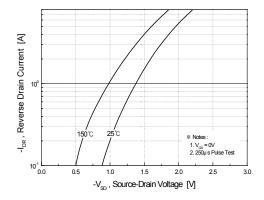


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

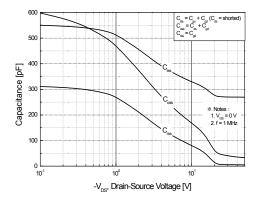


Figure 5. Capacitance Characteristics

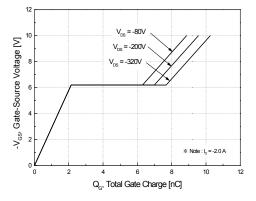
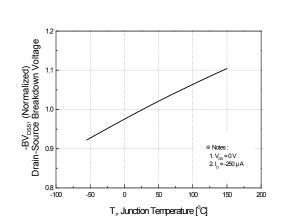


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

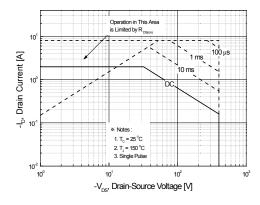
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(Nomalized Operation 1.5

Operation 1.0

Operati

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



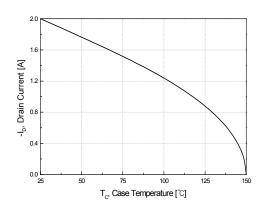


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

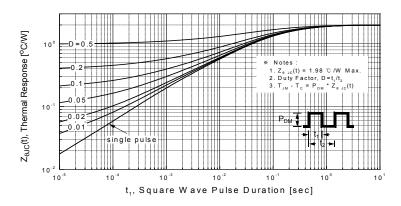


Figure 11. Transient Thermal Response Curve

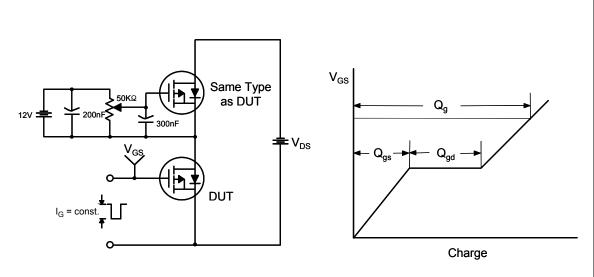


Figure 12. Gate Charge Test Circuit & Waveform

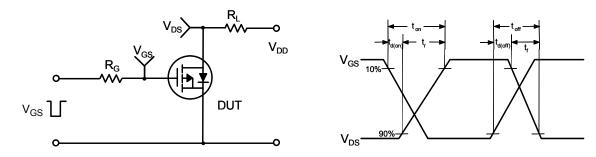


Figure 13. Resistive Switching Test Circuit & Waveforms

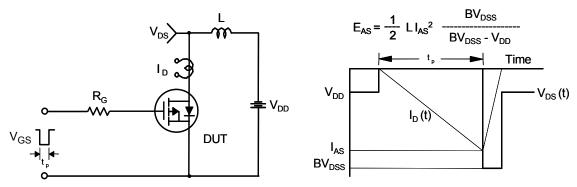
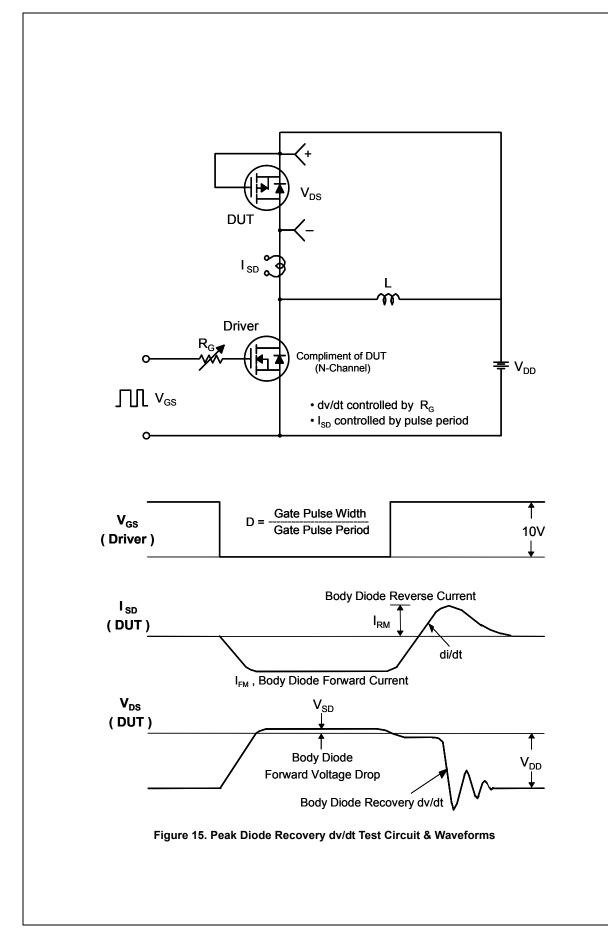
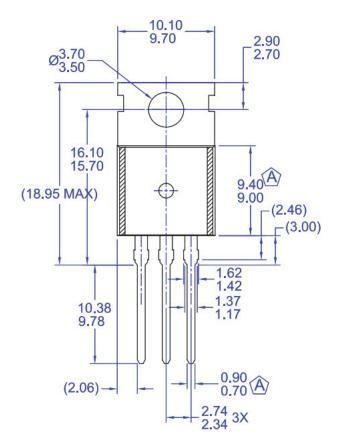
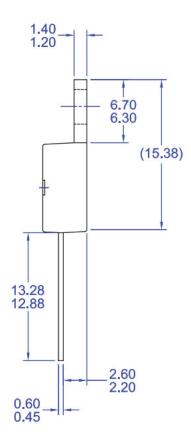


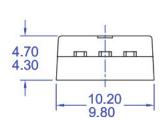
Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions







NOTES:

- (A) CONFORMS TO JEDEC TO-220 VARIATION AB EXCEPT WHERE NOTED
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DRAWING FILE/REVISION: MKT-TO220Y03REV1

Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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